



SOT1362-1

HWSON4: plastic thermal enhanced very very thin small outline package; no leads; 4 terminals; body 2.0 x 2.0 x 0.75 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	HWSON4
Package type industry code	HWSON4
Package style descriptive code	HWSON (thermal enhanced very very thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	---
JEDEC package outline code	MO-229
JEITA package outline code	---
Mounting method type	S (surface mount)
Issue date	20-11-2013

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		1.9	-	2	2.1	mm
E	package width		1.9	-	2	2.1	mm
A	seated height		0.7	-	0.75	0.8	mm
e	nominal pitch		-	-	0.95	-	mm
n ₂	actual quantity of termination		-	-	4	-	

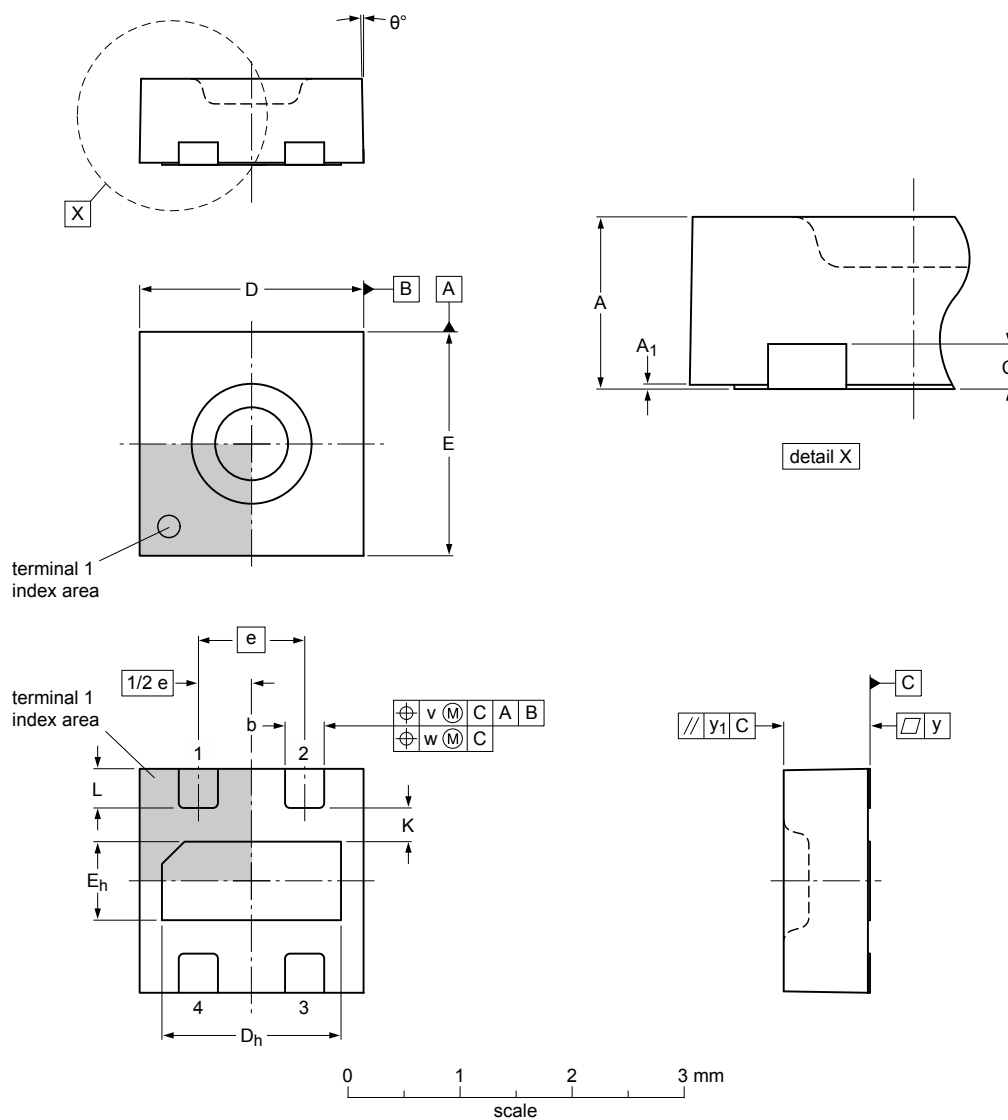


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2. Package outline

**HWSON4: plastic thermal enhanced very very thin small outline package; no leads;
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Dimensions (mm are the original dimensions)

Unit	A	A ₁	b	C	D ⁽¹⁾	D _h	E ⁽¹⁾	E _h	e	K	L	v	w	y	y ₁	θ°
mm	max	0.80	0.05	0.40		2.1	1.70	2.1	0.80		0.40					12°
	nom	0.75	0.02	0.35	0.203	2.0	1.60	2.0	0.70	0.95	0.35	0.1	0.05	0.05	0.1	
	min	0.70	0.00	0.30		1.9	1.50	1.9	0.60	0.20	0.30					0°

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

sot1362-1 po


Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1362-1		MO-229				13-11-18 13-11-20

Fig. 1. Package outline HWSO4 (SOT1362-1)

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3. Legal information

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4. Contents

1. Package summary..... 1

2. Package outline..... 2

3. Legal information..... 3

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